

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT6819779

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHIQUN GU	07/25/2018
TIEJUN LIU	09/12/2018
ZHAO CHEN	09/12/2018
RECEIVING PARTY DATA	
Name:	FUTUREWEI TECHNOLOGIES, INC.
Street Address:	5700 TENNYSON PARKWAY, SUITE 600
City:	PLANO
State/Country:	TEXAS
Postal Code:	75024
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15877283
CORRESPONDENCE DATA	
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Address Line 4:	DALY CITY, CALIFORNIA 94014
ATTORNEY DOCKET NUMBER:	FTRW-01232US0
NAME OF SUBMITTER:	LARRY E. VIERRA
SIGNATURE:	/Larry E. Vierra/
DATE SIGNED:	07/19/2021
Total Attachments: 3	
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ASSIGNMENT

WHEREAS, We, the undersigned inventors (or one of the undersigned joint inventors), of residence as listed below, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Futurewei Technologies, Inc. ("Assignee"), a corporation organized and existing under the laws of Texas, with its principal office at 5700 Tennyson Parkway, Suite 600, Plano, TX 75024 is desirous of acquiring my/our entire right, title and interest in the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

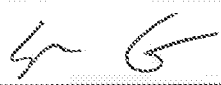
NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, we will assign, and hereby assign and transfer to the Assignee and the Assignee's legal representatives, successors and assigns the full and exclusive right, title and interest in and to the invention in the United States and every foreign country and the entire right, title, and interest in and to the patent application and other such applications (e.g., provisional applications, non-provisional applications, continuations, continuations-in-part, divisional, reissues, reexaminations, National Phase applications, including petty patent applications, and utility model applications) that may be filed in the United States and every foreign country on the invention, and the patents, extensions, or derivations thereof, both foreign and domestic, that may issue thereon, and I/we do hereby authorize and request the Commissioner for Patents to issue U.S. patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the Assignee agreeably with the terms of this assignment document.

We also hereby agree to sell and to assign, and sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

We hereby further agree that we will communicate to Assignee, or its successors, assigns, and legal representative, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid such Futurewei, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

ASSIGNMENT

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

Title of Invention	WRAPPED SIGNAL SHIELDING IN A WAFER FANOUT PACKAGE	
	Appl. No. <u>15/877,283</u>	Filing Date: <u>January 22, 2018</u>
Signature of Inventor		
Inventor Name	Shiqun Gu	
Date	<u>7/25/2018</u>	
Residence (City/State)	San Diego, CA	
Signature of Inventor		
Inventor Name	Tiejun Liu	
Date		
Residence (City/State)	Shenzen, China	
Signature of Inventor		
Inventor Name	Zhao Chen	
Date		
Residence (City/State)	Shenzen, China	

ASSIGNMENT

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

Title of Invention	WRAPPED SIGNAL SHIELDING IN A WAFER FANOUT PACKAGE	
	Appl. No. <u>15/877,283</u>	Filing Date: <u>January 22, 2018</u>
Signature of Inventor		
Inventor Name	Shiqun Gu	
Date		
Residence (City/State)	San Diego, CA	
Signature of Inventor	<i>Tiejun Liu</i>	
Inventor Name	Tiejun Liu	
Date	<i>09/12/2018</i>	
Residence (City/State)	Shenzen, China	
Signature of Inventor	<i>Zhao Chen</i>	
Inventor Name	Zhao Chen	
Date	<i>09/12/2018</i>	
Residence (City/State)	Shenzen, China	